

## **REVOCATION AND POWER OF ATTORNEY**

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

SIR:

EKC Technology, Inc., owner of the entire right, title and interest in, to and under the inventions described and claimed in the patent applications identified in the attached Schedule A, hereby revokes all previous powers of attorney and appoints Morgan, Lewis & Bockius LLP, customer no. 24341, and each of them, its attorneys, to prosecute each of these patent applications, and to transact all business in the Patent and Trademark Office connected therewith.

Please direct all future correspondence to Customer Number 24341, Morgan, Lewis & Bockius LLP, located at 3300 Hillview Avenue, Palo Alto, California 94304, and direct all telephone calls to Morgan, Lewis & Bockius LLP at (650) 493-4935.

Assignee:

EKC Technology, Inc.

Date

7 feb 2004

Signature:

Michael A. Fury

Typed Name: Position/Title:

Vice President, R&D and Engineering

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## Schedule A

CEM & TRIV					The state of the s
App.#		Inventor(s)	Filing Date	New/Attorney Docket/No	Former Attorney Docket No.
1	Compositions for Cleaning Organic		-		
00/000 004	and Plasma Etched Residues for	0	07/10/222		
09/903,064	Semiconductor Devices	Small, et al.	07/10/2001	60937-091-US	8317-091-999
00/074 220	Method of and Apparatus for Substrate Pre-Treatment	Malanau at al	00/00/0004	60007 444 110	0047 444 000
09/874,330	Chemical Mechanical Polishing	Maloney, et al.	06/06/2001	60937-111-US	8317-111-999
09/985,870	Compositions	Small, et al.	11/06/2001	60937-114-US	8317-114-999
	Oxalic Acid as a Semiaqueous	Oman, or an	11/00/2001	00007-114-00	0317-114-999
	Cleaning Product for Copper and				
10/421,706	Dielectrics	Lee, et al.	04/24/2003	60937-116-US	8317-116-999
	Sulfoxide Pyrolid(in)one Alkanolamine				
10/193,185	Cleaner Composition	Zhou, et al.	07/12/2002	60937-118-US	8317-118-999
00/075	Method for the Deposition of Materials	1			
09/876,944	from Mesomorphous Films	Vasquez, et al.	06/08/2001	60937-120-US	8317-120-999
10/007 124	Post Etch Cleaning Composition for	D	40/04/0004	00007 400 110	2017 100 000
10/007,134	Dual Damascene System Photolytic Conversion Process to	Payne, et al.	12/04/2001	60937-123-US	8317-123-999
10/263,701	Form Patterned Amorphous Film	Bravo-Vasquez, et al.	10/04/2002	60937-126-US	8317-126-999
10/200,701	Cleaning Solutions Including	Dravo-vasquez, et al.	10/04/2002	00937-120-03	0317-120-999
	Nucleophilic Amine Compound				:
	Having Reduction and Oxidation				
09/988,545	Potential	Lee, et al.	11/20/2001	60937-127-US	8317-127-999
	Method and Compositions for				
	Chemically Treating A Substrate			·	
10/060,109	Using Foam Technology	Patel, et al.	01/28/2002	60937-129-US	8317-129-999
	Cleaning Solution Including				
	Nucleophilic Amine Compound				
10/135,695	Having Reduction and Oxidation Potential	l ac at al	05/04/2002	60027 425 116	0047 405 000
10/135,695	Fluoride Layer and Removing Same	Lee, et al.  Melvin K. Carter	05/01/2002	60937-135-US	8317-135-999
10/440,127		ivieiviii N. Carter	05/30/2003	60937-137-US	8317-137-999
	Process for the Use of Bis-Choline and Tris-Choline in the Cleaning of				
	Quartz-Coated Polysilicon and Other				
10/689,657	Materials	Charm, et al.	10/22/2003	60937-139-US	8317-139-999
10,000,007	Cleaning Compositions Containing	Onaim, et al.	1012212003	00901-108-00	0011-108-888
	Hydroxylamine Derivatives and				
	Process Using Same for Residue				
10/689,620	Removal	Zhou, et al.	10/22/2003	60937-140-US	8317-140-999
10/05	Composition for Exfoliation Agent to				
10/689,616	be Used to Remove Resist Residues	Melvin K. Carter	10/22/2003	60937-141-US	8317-141-999
	Reducing Oxide Loss When Using				
	Fluoride Chemistries to Remove Post- Etch Residues in Semiconductor				
60/467,131	Processing	Lea atal	05/02/2002	60037 442 DD	9317 142 000
00/40/,131	Frocessing	Lee, et al.	05/02/2003	60937-142-PR	8317-142-888

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App #	Title	a Inventor(s)	Filing Date	New Attorney Docket No	Former Attorney Docket No.
	Method for Depositing Patterned				
10/630,301	Films of Materials	Hill, et al.	07/30/2003	60937-143-US	8317-143-999
	Methods for the Deposition of Silver				
	and Silver Oxide Films and Patterned				
10/716,838	Films	Ruan, et al.	11/18/2003	60937-147-US	8317-147-999
	Semiconductor Process Residue				
10/162,679	Removal Composition and Process	Lee, et al.	06/06/2002	60937-149-US	8317-149-999
	System and Method for Cleaning				
	Workpieces Using Supercritical				
60/469,826	Carbon Dioxide	Fury, et al.	05/13/2003	60937-150-PR	8317-150-888
	Abrasive-Free Chemical Mechanical				
	Polishing Composition and Polishing				
10/689,043	Process Containing Same	Yao, et al.	10/21/2003	60937-151-US	8317-151-999
10/689,042	Wet Etch of Titanium-Tungsten Film	Patel, et al.	10/21/2003	60937-152-US	8317-152-999
	Method of Depositing Nanostructured				•
10/261,197	Films with Embedded Nanopores	Svendsen, et al.	09/30/2002	60937-153-US	8317-153-999
	Hydrothermal Treatment of				
10/280,270	Nanostructured Films	Mukherjee, et al.	10/23/2002	60937-167-US	8317-167-999
10/257,469	Inhibition of Titanium Corrosion	Daviot, et al.	10/11/2002	60937-168-US	8317-168-999
40/404 405	Chemical Mechanical Polishing				
10/401,405	Composition andProcess	Small, et al.	03/27/2003	60937-171-US	8317-171-999
	Aqueous Phosphoric Acid				
40/000 000	Compositions for Cleaning	5	40/04/0000	22227 172 112	
10/688,900	Semiconductor Devices	Daviot, et al.	10/21/2003	60937-172-US	8317-172-999
10/465 006	Load Lock System for Supercritical	F4 -1	00/40/0000	00007 475 110	0047 475 000
10/465,906	Fluid Cleaning Automated Dense Phase Fluid	Fury, et al.	06/18/2003	60937-175-US	8317-175-999
10/465,905		Funzat at	06/49/2002	60007 476 116	0047 470 000
10/403,903	Cleaning System  Residue Removers for	Fury, et al.	06/18/2003	60937-176-US	8317-176-999
	Electrohydrodynamic Cleaning of	•			
60/455,439	Semiconductors	Robert J. Small	03/18/2003	60937-178-PR	0247 470 000
00/400,409		Robert J. Small	03/16/2003	00937-170-PK	8317-178-888
	Free Radical-Forming Activator				
40/204 000	Attached to Solid and Used to	0 "	00/44/0000		
10/361,822	Enhance CMP Formulations	Scott, et al.	02/11/2003	60937-179-US	8317-179-999
10/277 522	Titanium Carboxylate Films for Use in	1 1:10 -4 -4	00/00/0000	00007 400 440	0047 400 000
10/377,533	Semiconductor Processing	Hill, et al.	02/26/2003	60937-182-US	8317-182-999
10/422,860	Method of Making Barrier Layers Remover Formulation Containing	Maloney, et al.	05/20/2003	60937-183-US	8317-183-999
:	Fluoride for Use During				
60/463,739	Semiconductor Manufacturing	Hirasawa, et al.	04/18/2003	60037 195 DD	9217 105 000
30/400,709	Cleaning Composition for Removing	i iliasawa, et al.	04/10/2003	60937-185-PR	8317-185-888
	Resists and Manufacturing Method of				
60/464,125	Semiconductor Devices	Hirasawa, et al.	04/21/2003	60937-186-PR	8317-186-888
30, 10 1, 120	Deposition of Permanent Polymer	i ili asawa, et al.	04/2/1/2003	00337-100-FR	0317-100-000
10/422,212	Structures for OLED Fabrication	Roman, et al.	04/23/2003	60937-187-US	8317-187-999
	Tablication	roman, et al.	1 07/20/2000	1 30331-101-03	0017-107-999

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	Title	Inventor(s);	Filing Date	New/Attorney = Docket No ;	Former Attorney ∴ Docket No.
	Seimconductor Process Residue				
10/442,858	Removal Composition and Process	Wai Mun Lee	05/20/2003	60937-189-US	8317-189-999
	Cleaning Compositions and Method of				
10/630,300	Use Thereof	Wai Mun Lee	07/30/2003	60937-194-US	8317-194-999
	Compositions and Methods for				
	Rapidly Removing Overfilled				
60/518,337	Substrates	Chelle, et al.	11/10/2003	60937-200-PR	8317-200-888
	CMP Method for Copper, Tungsten,				
	Titanium, Polysilicon, and Other				
	Substrates Using Organosulfonic				
10/690,623	Acids as Oxidizers	Carter, et al.	10/23/2003	60937-202-US	8317-202-999
	PeriodicAcid Compositions for				
00/404 054	Polishing Nobel Metal/High K	D = 1 = -4 1 011	00/44/0000		0047 000 000
60/494,954	Substrates Cerium Oxide Abrasives for Chemical	Robert J. Small	08/14/2003	60937-203-PR	8317-203-888
60/509,920	Mechanical Polishing	Robert J. Small	10/10/2003	60937-204-PR	0247 204 000
00/309,920	Mechanical Folishing	Robert J. Siliali	10/10/2003	00937-204-PR	8317-204-888
	Chemical Mechanical Polishing				
	Slurries and Cleaners Containing				
60/516,736	Salicyclic Acid as a Corrosion Inhibitor	Carter, et al.	11/04/2003	60937-206-PR	8317-206-888
	Periodic Acid Compositions for		1.101/2000	00007 200 1 10	200 000
60/494,955	Polishing Ruthenium Substrates	Robert J. Small	08/14/2003	60937-207-PR	8317-207-888
	Chemical Mechanical Polishing				
10/683,730	Compositions and Process	Small, et al.	10/10/2003	60937-211-US	8317-211-999
	Alumia Abrasive for Chemical				
60/514,020	Mechanical Polishing	Philippe H. Chelle	10/27/1999	60937-213-PR	8317-213-888
	Chemical Mechanical Polishing				
	Slurries and Cleaners Containing				
60/502,951	Salicyclic Acid as a Corrosion Inhibitor	Tamilmani, et al.	09/16/2003	60937-214-PR	8317-214-888
	Compositions for Chemical				
10/005 447	Mechanical Planarization of Tantalum	0	00/00/0000	00007 045 110	0047.045.000
10/665,417	and Tantalum Nitride	Small, et al.	09/22/2003	60937-215-US	8317-215-999
60/526,107	Alumina Abrasive for Chemical Mechanical Polishing	Chelle, et al.	12/02/2003	60937-216-PR	8317-216-888
30/320,10/	Particulate or Particle-Bound	Oneile, et al.	12/02/2003	00331-210-FR	0317-210-000
60/509,922	Chelating Agents	Small, et al.	10/10/2003	60937-217-PR	8317-217-888
00,000,022	Particulate or Particle-Bound	Oman, or al.	10/10/2000	00001 211 110	0011 211 000
10/690,626	i e	Small, et al.	10/23/2003	60937-217-US	8317-217-999
	Chemical Mechanical Polishing of STI				
	Features on Semiconductors: Water				
60/533,054	Polishing with Ceria Slurries	Yu, et al.	12/30/2003	60937-223-PR	8317-223-888
	Removal of Post Etch Residues and				
1	Copper Contamination From Low-K				
	Dielectrics Using Superciritcal CO2				
60/511,949	with Diketone Additives	Jerome Daviot	10/14/2003	60937-225-PR	8317-225-888
10/004 005	Method and Apparatus for Substrate		10/00/0555	00007-057-117	
10/694,999	Pre-Treatment	Lee, et al.	10/29/2003	60937-226-US	8317-226-999

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	Method of Chemically Mechanically			·	
60/515,450	Polishing Substrates	Brandon S. Scott	10/30/2003	60937-228-PR	8317-228-888

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